IN THE CLAIMS:

Claims 1-10, and 12-27 have been amended. All of the pending claims 1 through 27 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Currently Amended) A method of fabricating a substrate assembly, comprising:
providing a substrate having a first surface and an opposing second surface;
forming a layer of resilient conductive material on at least a portion of at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate;
forming at least one electrically isolated spring-biased electrical contact in ~~said~~ the layer of resilient conductive material;
forming at least one electrically isolated conductive trace in ~~said~~ the layer of resilient conductive material, ~~said~~ the at least one electrically isolated conductive trace having an end terminating at ~~said~~ the at least one electrically isolated spring-biased electrical contact; and
treating ~~said~~ the layer of resilient conductive material after ~~said~~ forming ~~said~~ the at least one electrically isolated spring-biased electrical contact to achieve at least one desired physical characteristic of ~~said~~ the layer of resilient conductive material.

2. (Currently Amended) The method of claim 1, wherein ~~said~~ forming a layer of resilient conductive material on at least a portion of at least one of ~~said~~ the first and second surface of ~~said~~ the substrate comprises:
providing a laminate sheet of ~~said~~ the resilient conductive material; and
bonding ~~said~~ the laminate sheet to ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate.

3. (Currently Amended) The method of claim 2, wherein ~~said~~ bonding ~~said~~ the laminate sheet to ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate

comprises adhering ~~said~~ the laminate sheet to ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate using an adhesive or bonding ~~said~~ the laminate sheet to ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate using a thermocompression bonding process.

4. (Currently Amended) The method of claim 1, wherein ~~said~~ forming a layer of resilient conductive material on at least a portion of at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate comprises forming ~~said~~ the layer of resilient conductive material on ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate using a deposition process.

5. (Currently Amended) The method of claim 4, wherein ~~said~~ the deposition process comprises chemical vapor deposition or sputtering.

6. (Currently Amended) The method of claim 1, further comprising forming at least one via in ~~said~~ the substrate, ~~said~~ the at least one via underlying ~~said~~ the at least one electrically isolated spring-biased electrical contact.

7. (Currently Amended) The method of claim 6, wherein ~~said~~ forming at least one via in ~~said~~ the substrate further comprises forming a via opening only to ~~said~~ the at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate.

8. (Currently Amended) The method of claim 1, further comprising preforming ~~said~~ the at least one electrically isolated spring-biased electrical contact to include a permanent deflection.

9. (Currently Amended) The method of claim 1, further comprising forming at least one contact element on a surface of ~~said~~ the at least one electrically isolated spring-biased electrical contact.

10. (Currently Amended) The method of claim 9, wherein ~~said~~ forming at least one contact element further comprises forming a plurality of alternating grooves and ridges, forming at least one protrusion, or forming a roughened surface.

11. (Original) The method of claim 10, wherein forming a plurality of alternating grooves and ridges, forming at least one protrusion or forming a roughened surface is effected by etching.

12. (Currently Amended) The method of claim 1, wherein ~~said~~ forming at least one electrically isolated spring-biased electrical contact in ~~said~~ the layer of resilient conductive material comprises forming a cantilevered spring, forming a transversely deflecting hoop-shaped spring, forming a spiral-shaped spring, or forming a rosette spring.

13. (Currently Amended) The method of claim 1, wherein at least one of forming at least one electrically isolated spring-biased electrical contact in ~~said~~ the layer of resilient conductive material and forming at least one electrically isolated conductive trace in ~~said~~ the layer of resilient conductive material is effected by etching ~~said~~ the layer of resilient conductive material.

14. (Currently Amended) A method of fabricating a substrate assembly, comprising:
providing a substrate having a first surface and an opposing second surface;
forming a layer of resilient conductive material on at least a portion of at least one of ~~said~~ the first and second surfaces of ~~said~~ the substrate, ~~said~~ the resilient conductive material exhibiting at least one first physical characteristic;

forming at least one electrically isolated spring-biased electrical contact in ~~said~~ the layer of resilient conductive material;

forming at least one electrically isolated conductive trace in ~~said~~ the layer of resilient conductive material, ~~said~~ the at least one electrically isolated conductive trace having an end terminating at ~~said~~ the at least one electrically isolated spring-biased electrical contact; and

treating ~~said~~ the layer of resilient conductive material to achieve at least one second physical characteristic of ~~said~~ the resilient conductive material.

15. (Currently Amended) The method of claim 14, wherein ~~said~~ the at least one first physical characteristic is selected to optimize properties of ~~said~~ the layer of resilient conductive material for ~~said~~ the act of forming at least one electrically isolated spring-biased electrical contact therein.

16. (Currently Amended) The method of claim 14, wherein ~~said~~ the at least one second physical characteristic is selected to optimize spring characteristics of ~~said~~ the at least one electrically isolated spring-biased electrical contact.

17. (Currently Amended) The method of claim 14, wherein at least one of forming at least one electrically isolated spring-biased electrical contact in ~~said~~ the layer of resilient conductive material and forming at least one electrically isolated conductive trace in ~~said~~ the layer of resilient conductive material is effected by etching ~~said~~ the layer of resilient conductive material.

18. (Currently Amended) The method of claim 1, further including disposing a dielectric layer overlying ~~said~~ the layer of resilient conductive material, ~~said~~ the dielectric layer being formed with at least one aperture therethrough substantially aligned with ~~said~~ the at least one electrically isolated spring-biased electrical contact.

19. (Currently Amended) The method of claim 18, further comprising forming ~~said~~ the dielectric layer to be of sufficient thickness to encompass at least a portion of each lead element of an integrated circuit device contacting ~~said~~ the at least one electrically isolated spring-biased electrical contact.

20. (Currently Amended) The method of claim 18, further including forming ~~said~~ the at least one aperture to be of frustoconical configuration.

21. (Currently Amended) The method of claim 18, further including preforming ~~said~~ the dielectric layer with ~~said~~ the at least one aperture prior to disposing ~~said~~ the dielectric layer over ~~said~~ the layer of resilient conductive material.

22. (Currently Amended) The method of claim 18, further including forming ~~said~~ the dielectric layer in place over ~~said~~ the layer of resilient conductive material and subsequently forming ~~said~~ the at least one aperture therethrough.

23. (Currently Amended) The method of claim 14, further including disposing a dielectric layer over ~~said~~ the layer of resilient conductive material, ~~said~~ the dielectric layer being formed with at least one aperture therethrough substantially aligned with ~~said~~ the at least one electrically isolated spring-biased electrical contact.

24. (Currently Amended) The method of claim 23, further comprising forming ~~said~~ the dielectric layer to be of sufficient thickness to encompass at least a portion of each lead element of an integrated circuit device contacting ~~said~~ the at least one electrically isolated spring-biased electrical contact.

25. (Currently Amended) The method of claim 24, further including forming ~~said~~ the at least one aperture to be of frustoconical configuration.

26. (Currently Amended) The method of claim 23, further including preforming ~~said~~ the dielectric layer with ~~said~~ the at least one aperture prior to disposing ~~said~~ the dielectric layer over ~~said~~ the layer of resilient conductive material.

27. (Currently Amended) The method of claim 23, further including forming ~~said~~ the dielectric layer in place over ~~said~~ the layer of resilient conductive material and subsequently forming ~~said~~ the at least one aperture therethrough.